

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	80	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	57	V
Forward Continuous Current	I _{FM}	300	mA
Average Rectified Output Current	I _O	95	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	2.0
		@ t = 1.0s	1.0
			A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	250	mW
Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Conditions
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	80	—	V	I _R = 100μA
Forward Voltage	V _F	0.62	0.72	V	I _F = 5.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 100mA
		—	1.25		I _F = 150mA
Peak Reverse Current (Note 7)	I _R	—	100	nA	V _R = 80V
			50	μA	V _R = 75V, T _J = +150°C
			30	μA	V _R = 25V, T _J = +150°C
			25	nA	V _R = 20V
Total Capacitance	C _T	—	3.0	pF	V _R = 0.5V, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 × I _R , R _L = 100Ω

Notes: 6. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
7. Short duration pulse test used to minimize self-heating effect.

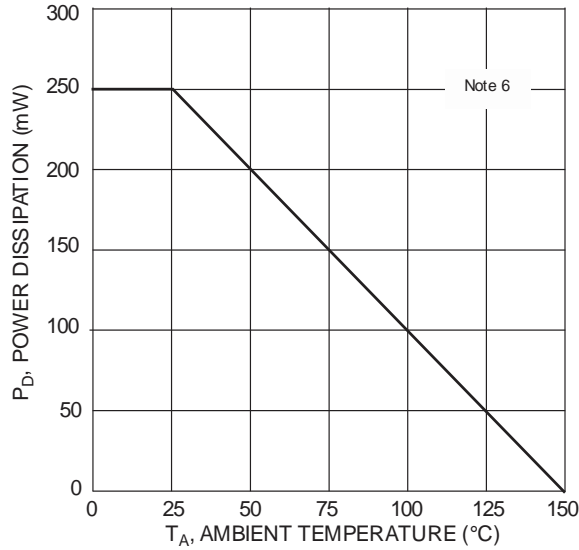


Fig. 1 Power Derating Curve

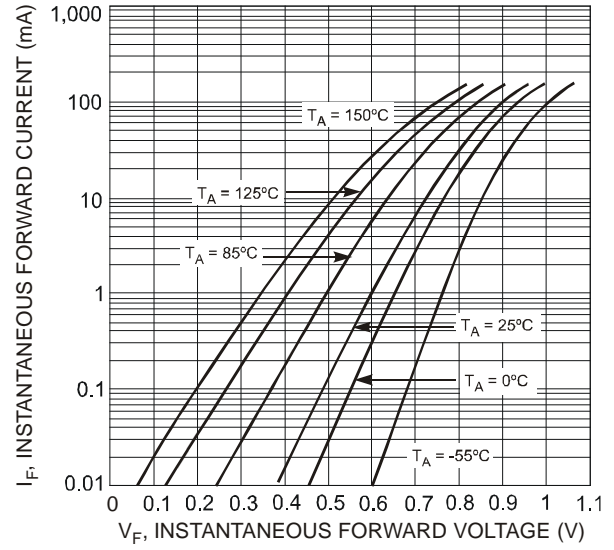


Fig. 2 Typical Forward Characteristics

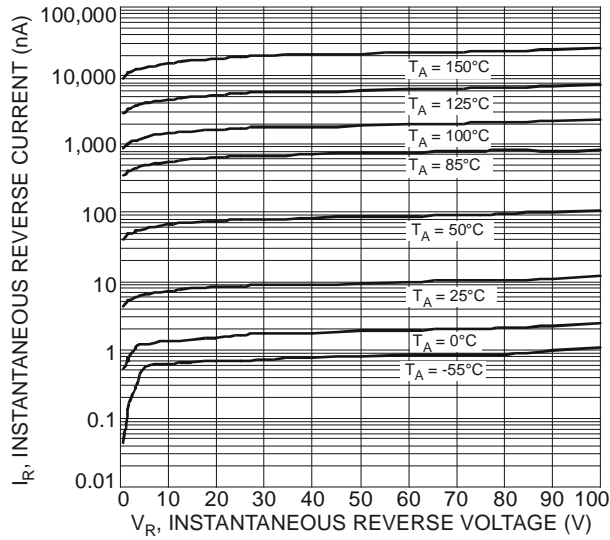


Fig. 3 Typical Reverse Characteristics

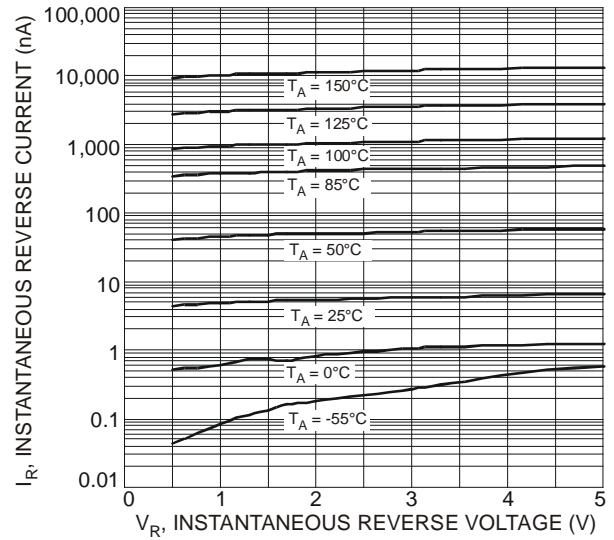


Fig. 4 Typical Reverse Characteristics - Low Bias

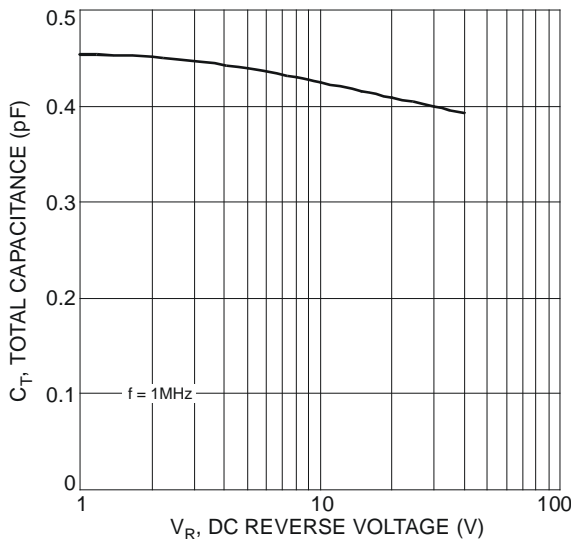


Fig. 5 Typical Total Capacitance vs. Reverse Voltage

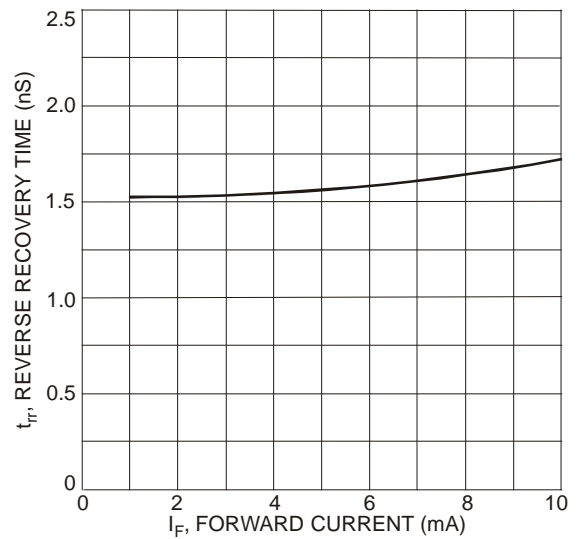
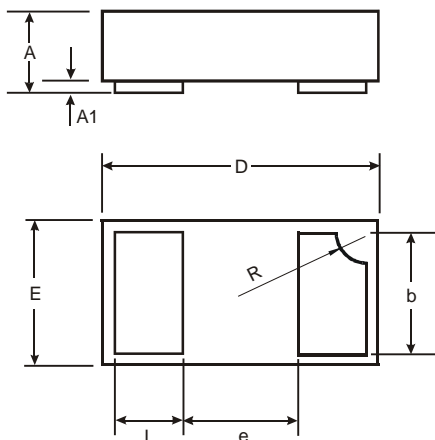


Fig. 6 Typical Reverse Recovery Time vs. Forward Current

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-2

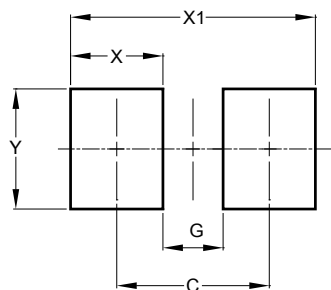


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Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X1-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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